

SOT2091-1

BGA360, ball grid array package, 360 terminals, 1 mm pitch,
23 mm x 23 mm x 2.25 mm body

5 November 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA360
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-10-2020
Manufacturer package code	98ASA01712D

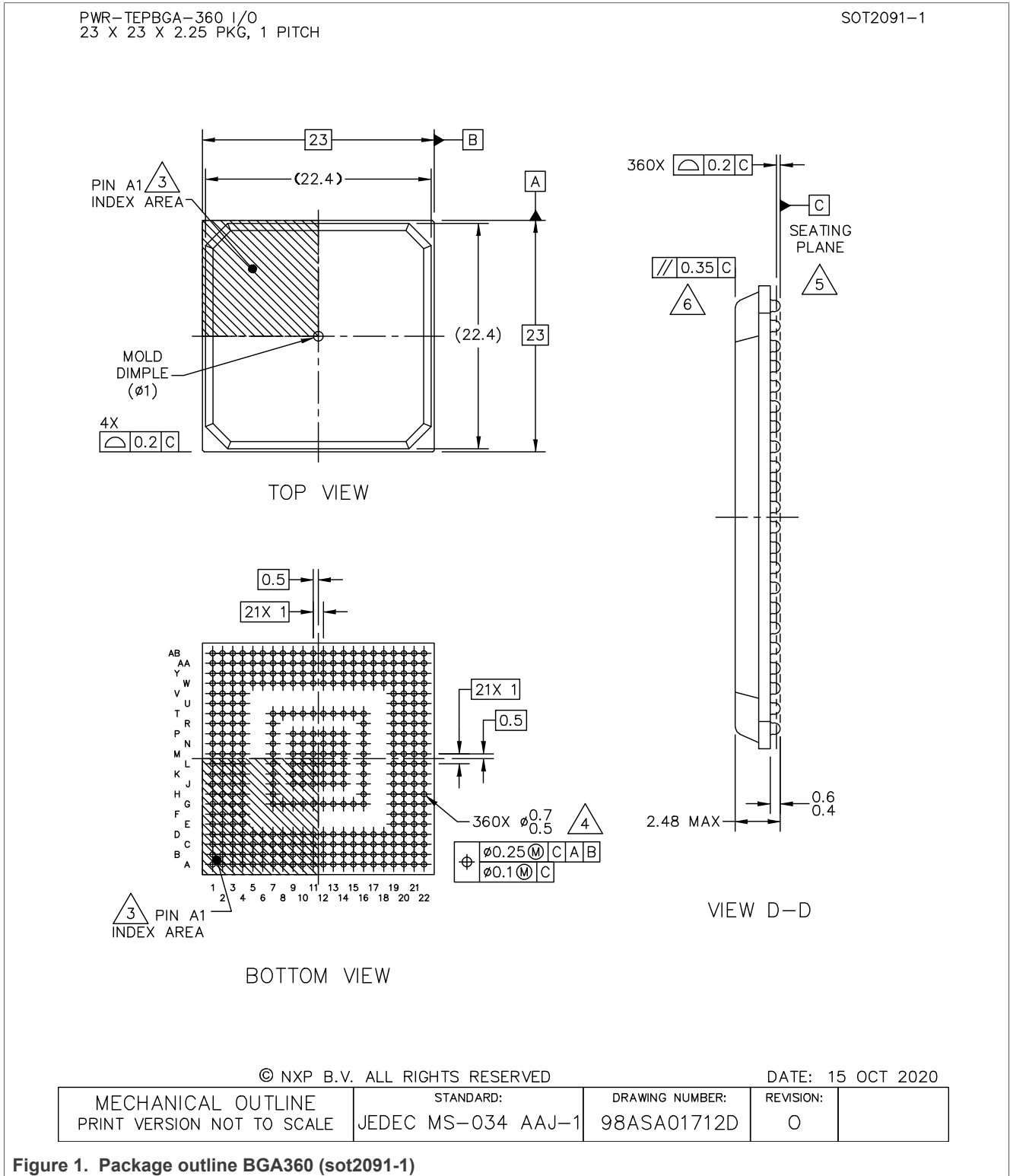
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	22.8	23	23.2	mm
package width	22.8	23	23.2	mm
package height	-	2.25	2.48	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	360	-	



BGA360, ball grid array package, 360 terminals, 1 mm pitch, 23 mm x 23 mm x 2.25 mm body

2 Package outline



3 Soldering

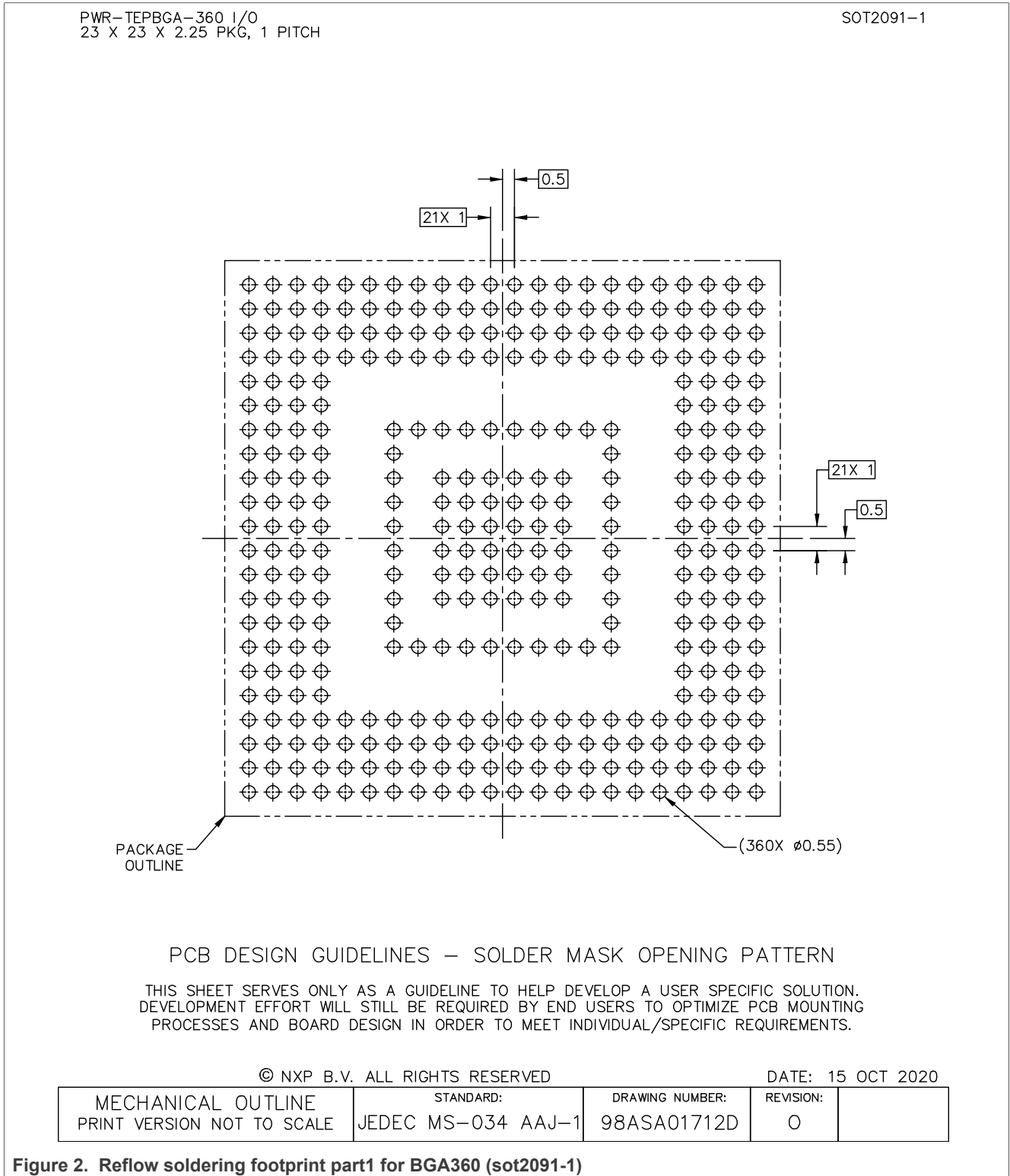
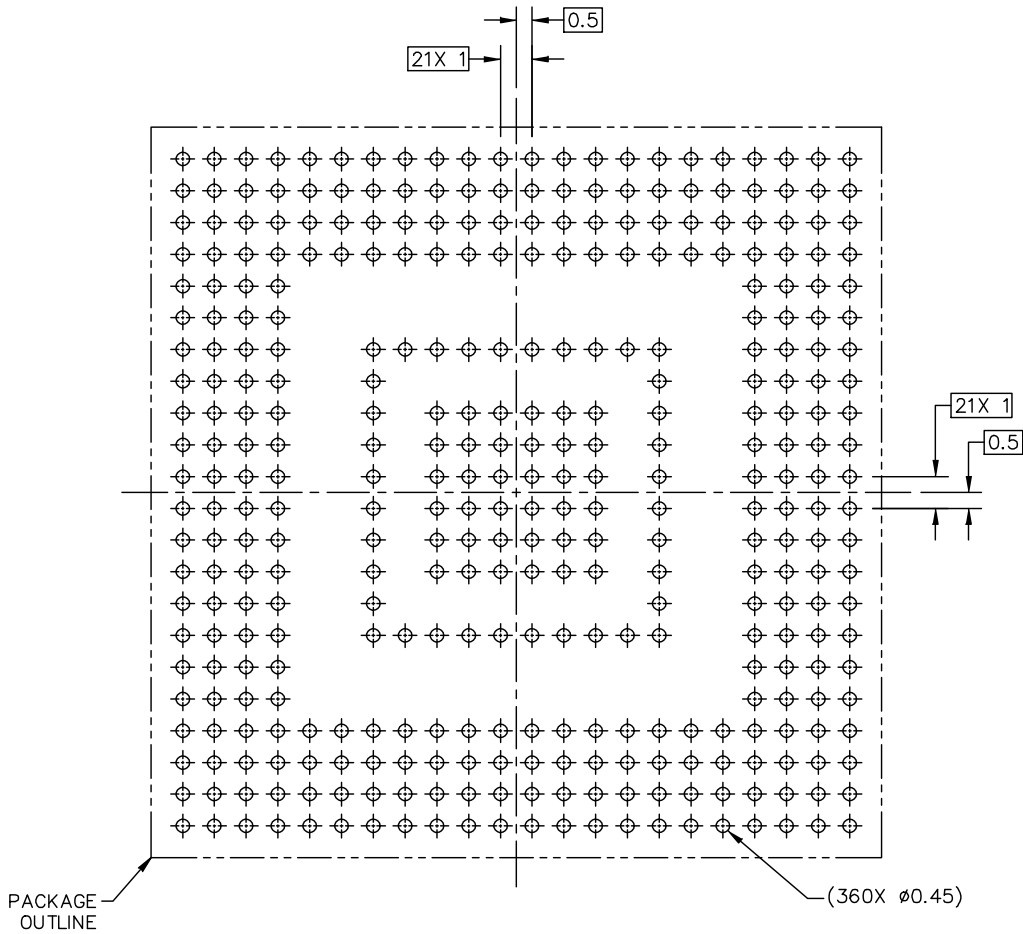


Figure 2. Reflow soldering footprint part1 for BGA360 (sot2091-1)

BGA360, ball grid array package, 360 terminals, 1 mm pitch, 23 mm x 23 mm x 2.25 mm body

PWR-TEPBGA-360 I/O
23 X 23 X 2.25 PKG, 1 PITCH

SOT2091-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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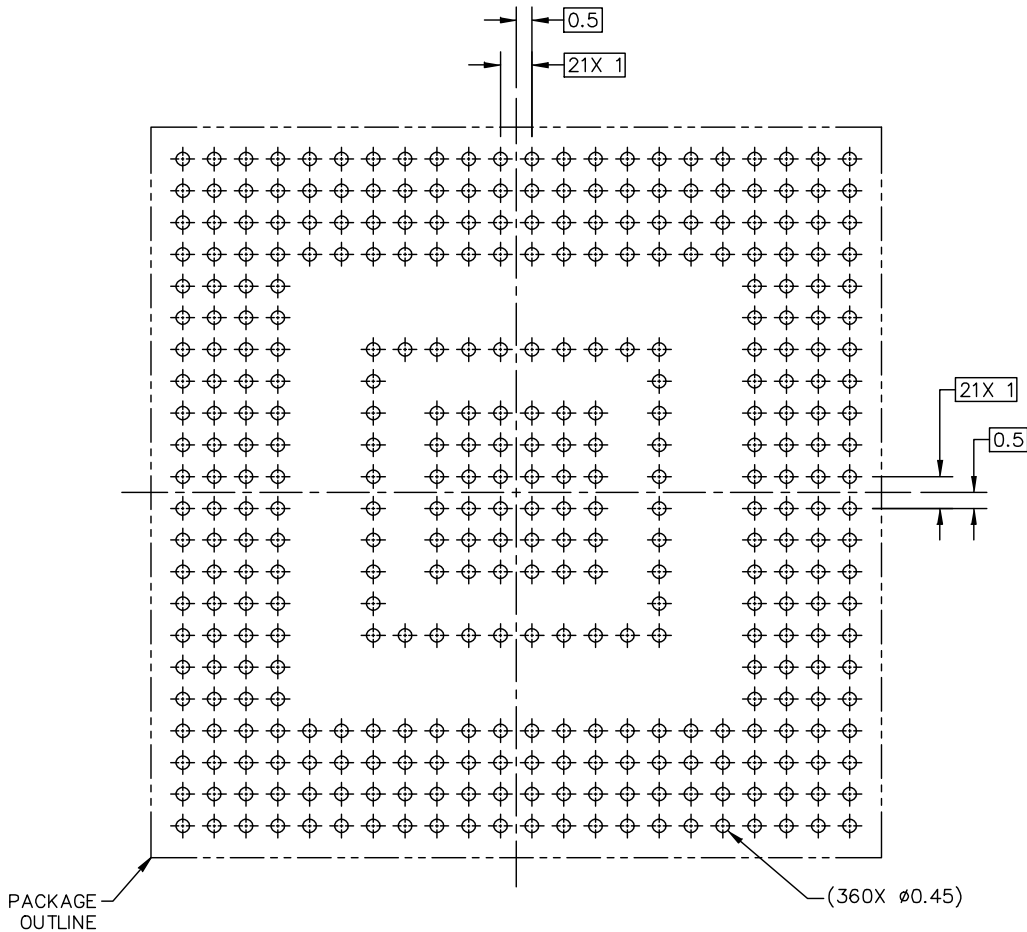
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS-034 AAJ-1	DRAWING NUMBER: 98ASA01712D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for BGA360 (sot2091-1)

BGA360, ball grid array package, 360 terminals, 1 mm pitch, 23 mm x 23 mm x 2.25 mm body

PWR-TEPBGA-360 I/O
23 X 23 X 2.25 PKG, 1 PITCH

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Figure 4. Reflow soldering footprint part3 for BGA360 (sot2091-1)

BGA360, ball grid array package, 360 terminals, 1 mm pitch, 23 mm x 23 mm x 2.25 mm body

PWR-TEPBGA-360 I/O
23 X 23 X 2.25 PKG, 1 PITCH

SOT2091-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note BGA360 (sot2091-1)

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